

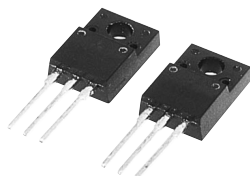
PRELIMINARY
 Notice: This is not a final specification.
 Some parametric limits are subject to change.

MITSUBISHI Pch POWER MOSFET

FX30KMJ-2

HIGH-SPEED SWITCHING USE

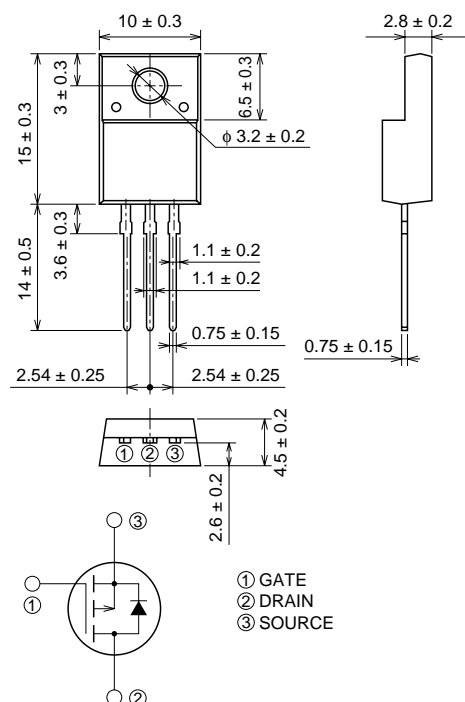
FX30KMJ-2



- 4V DRIVE
- V_{DS} -100V
- $r_{DS(ON)}(MAX)$ 0.143Ω
- I_D -30A
- Integrated Fast Recovery Diode (TYP.) 100ns
- V_{iso} 2000V

OUTLINE DRAWING

Dimensions in mm



TO-220FN

APPLICATION

Motor control, Lamp control, Solenoid control
 DC-DC converter, etc.

MAXIMUM RATINGS ($T_c = 25^\circ\text{C}$)

Symbol	Parameter	Conditions	Ratings	Unit
V_{DS}	Drain-source voltage	$V_{GS} = 0V$	-100	V
V_{GSS}	Gate-source voltage	$V_{DS} = 0V$	± 20	V
I_D	Drain current		-30	A
I_{DM}	Drain current (Pulsed)		-120	A
I_{DA}	Avalanche drain current (Pulsed)	$L = 30\mu H$	-30	A
I_S	Source current		-30	A
I_{SM}	Source current (Pulsed)		-120	A
P_D	Maximum power dissipation		30	W
T_{ch}	Channel temperature		$-55 \sim +150$	$^\circ\text{C}$
T_{stg}	Storage temperature		$-55 \sim +150$	$^\circ\text{C}$
V_{iso}	Isolation voltage	AC for 1minute, Terminal to case	2000	V
—	Weight	Typical value	2.0	g

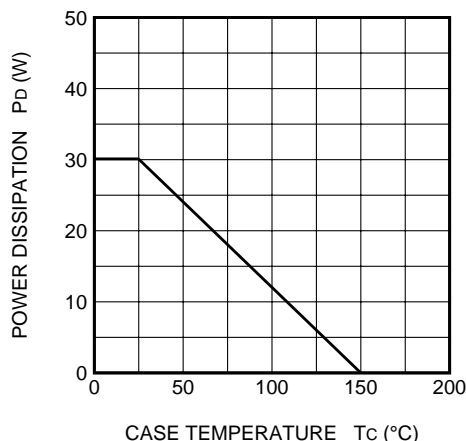
Jan.1999

ELECTRICAL CHARACTERISTICS ($T_{ch} = 25^{\circ}\text{C}$)

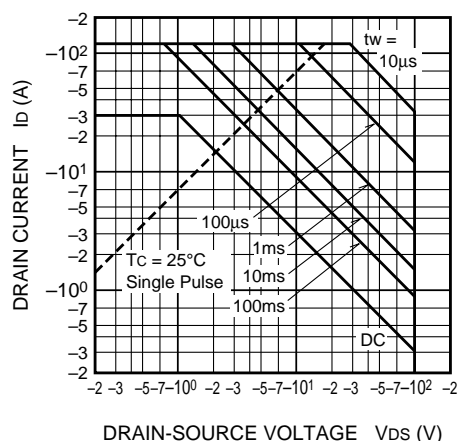
Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = -1\text{mA}$, $V_{GS} = 0\text{V}$	-100	—	—	V
I_{GSS}	Gate-source leakage current	$V_{GS} = \pm 20\text{V}$, $V_{DS} = 0\text{V}$	—	—	± 0.1	μA
I_{DSS}	Drain-source leakage current	$V_{DS} = -100\text{V}$, $V_{GS} = 0\text{V}$	—	—	-0.1	mA
$V_{GS(th)}$	Gate-source threshold voltage	$I_D = -1\text{mA}$, $V_{DS} = -10\text{V}$	-1.0	-1.5	-2.0	V
$r_{DS(on)}$	Drain-source on-state resistance	$I_D = -15\text{A}$, $V_{GS} = -10\text{V}$	—	0.113	0.143	Ω
$r_{DS(on)}$	Drain-source on-state resistance	$I_D = -15\text{A}$, $V_{GS} = -4\text{V}$	—	0.135	0.176	Ω
$V_{DS(on)}$	Drain-source on-state voltage	$I_D = -15\text{A}$, $V_{GS} = -10\text{V}$	—	-1.65	-2.15	V
$ y_{fs} $	Forward transfer admittance	$I_D = -15\text{A}$, $V_{DS} = -10\text{V}$	—	20	—	S
C_{iss}	Input capacitance	$V_{DS} = -10\text{V}$, $V_{GS} = 0\text{V}$, $f = 1\text{MHz}$	—	4450	—	pF
C_{oss}	Output capacitance		—	330	—	pF
C_{rss}	Reverse transfer capacitance		—	170	—	pF
$t_d(on)$	Turn-on delay time	$V_{DD} = -50\text{V}$, $I_D = -15\text{A}$, $V_{GS} = -10\text{V}$, $R_{GEN} = R_{GS} = 50\Omega$	—	16	—	ns
t_r	Rise time		—	54	—	ns
$t_d(off)$	Turn-off delay time		—	270	—	ns
t_f	Fall time		—	129	—	ns
V_{SD}	Source-drain voltage	$I_S = -15\text{A}$, $V_{GS} = 0\text{V}$	—	-1.0	-1.5	V
$R_{th(ch-c)}$	Thermal resistance	Channel to case	—	—	4.17	$^{\circ}\text{C/W}$
t_{rr}	Reverse recovery time	$I_S = -30\text{A}$, $di/dt = 100\text{A}/\mu\text{s}$	—	100	—	ns

PERFORMANCE CURVES

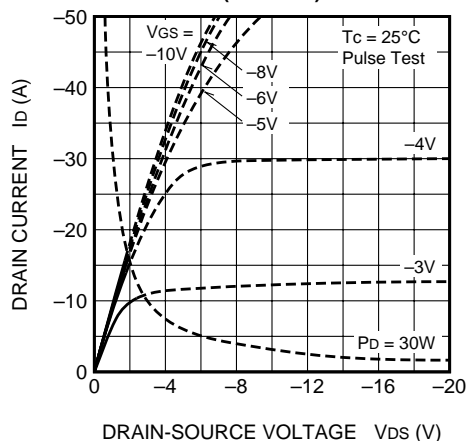
POWER DISSIPATION DERATING CURVE



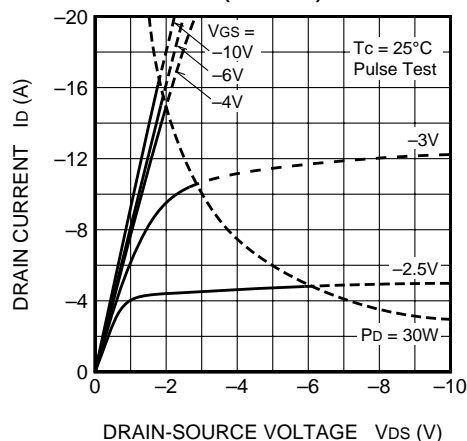
MAXIMUM SAFE OPERATING AREA



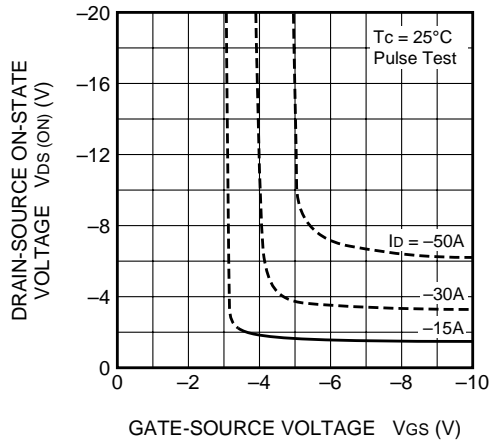
OUTPUT CHARACTERISTICS (TYPICAL)



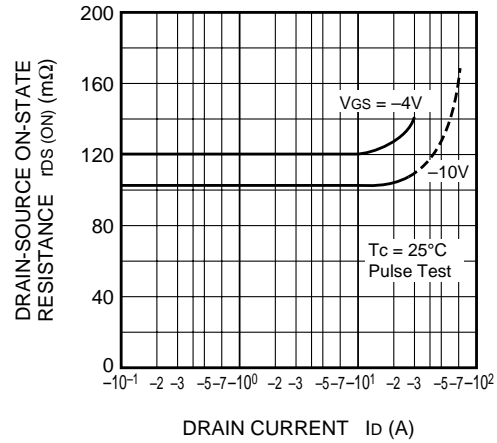
OUTPUT CHARACTERISTICS (TYPICAL)



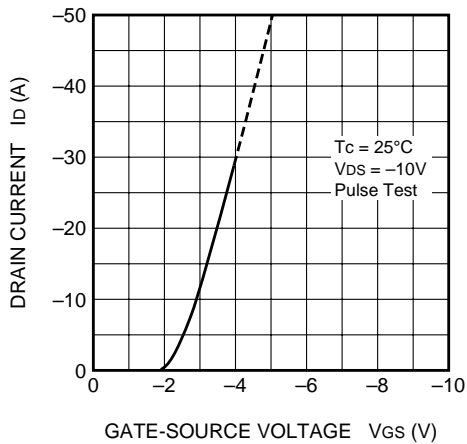
**ON-STATE VOLTAGE VS.
GATE-SOURCE VOLTAGE
(TYPICAL)**



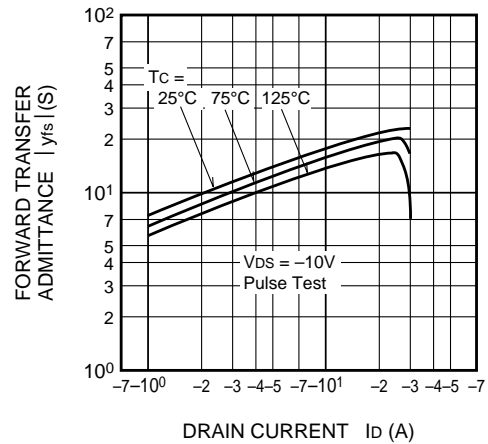
**ON-STATE RESISTANCE VS.
DRAIN CURRENT
(TYPICAL)**



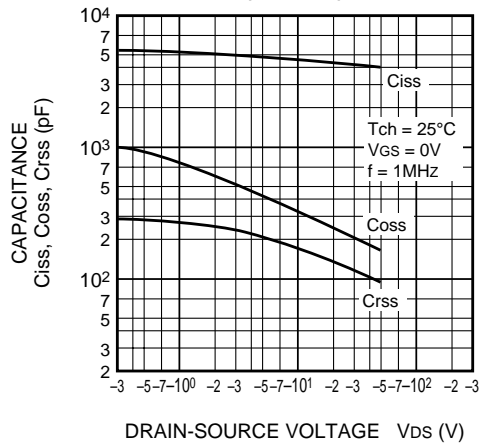
**TRANSFER CHARACTERISTICS
(TYPICAL)**



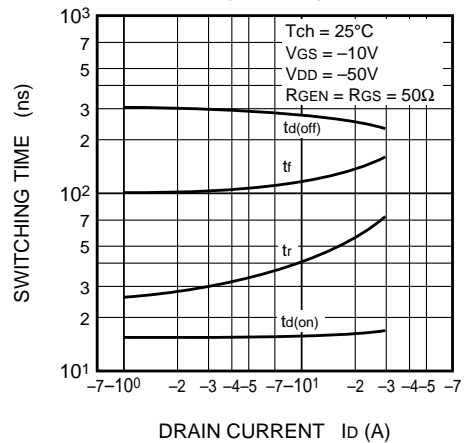
**FORWARD TRANSFER ADMITTANCE
VS. DRAIN CURRENT
(TYPICAL)**



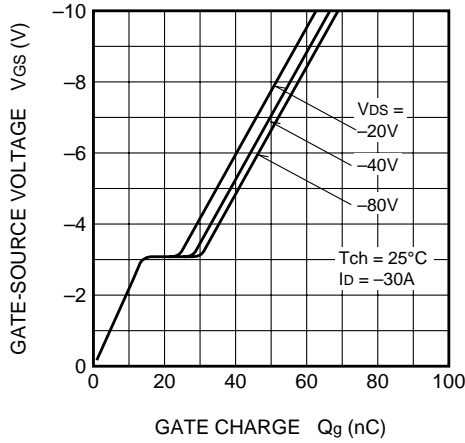
**CAPACITANCE VS.
DRAIN-SOURCE VOLTAGE
(TYPICAL)**



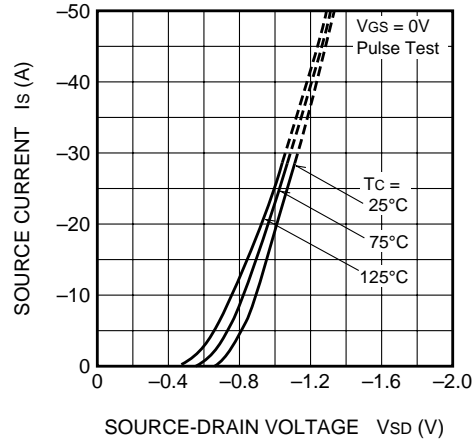
**SWITCHING CHARACTERISTICS
(TYPICAL)**



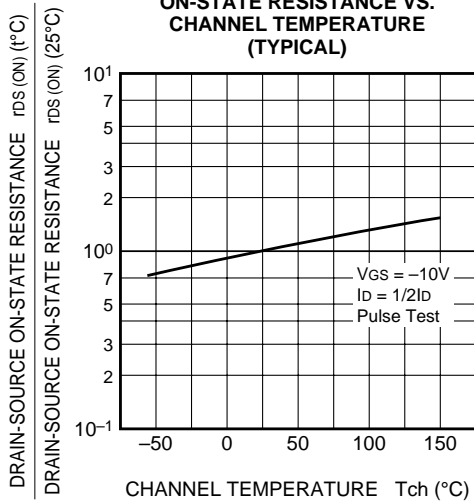
**GATE-SOURCE VOLTAGE
VS.GATE CHARGE
(TYPICAL)**



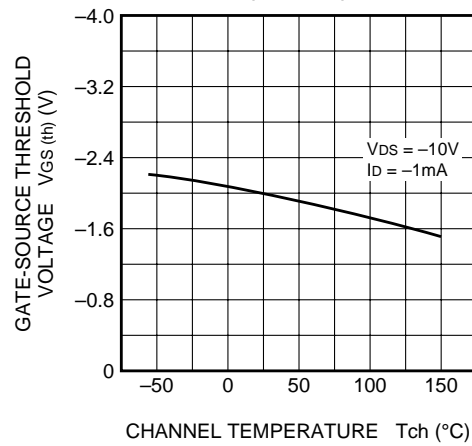
**SOURCE-DRAIN DIODE
FORWARD CHARACTERISTICS
(TYPICAL)**



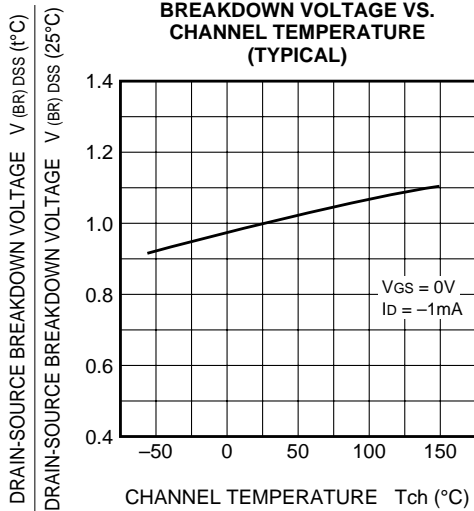
**ON-STATE RESISTANCE VS.
CHANNEL TEMPERATURE
(TYPICAL)**



**THRESHOLD VOLTAGE VS.
CHANNEL TEMPERATURE
(TYPICAL)**



**BREAKDOWN VOLTAGE VS.
CHANNEL TEMPERATURE
(TYPICAL)**



**TRANSIENT THERMAL IMPEDANCE
CHARACTERISTICS**

